

## Day 1 - Monday 7th April 2025

18:30 Pre-conference networking drinks reception

## Day 2 - Tuesday 8th April 2025

08:00 Registration and welcome refreshments

08:50 Housekeeping by Chris Meadows and Tim Bettles - Conference Chairs

### Expanding the emission envelope

09:00 **Expanding the Spectral Range of GaN-based SLEDs**

*Presented by Marco Malinverni - Exalos*

09:15 **Perfecting GaN VCSEL Production Process**

*Presented by Tetsuya Takeuchi - Meijo University*

09:30 **Connected Metrology for Growth and Characterization of InP and GaAs Laser Structures – from Epi to Etch**

*Presented by Iris Claussen - LayTec AG*

09:45 **Germanium as an Enabler for Large Volume Production in PV and Photonics**

*Presented by Ivan Zyulkov - Umicore*

10:00 **InP NIR VCSELS from 1.3 μm to beyond 2 μm for Single Mode and Multi Mode Applications**

*Presented by Christian Neumeyr - Vertilas*

10:15 **The Power of Pseudomorphic Nitrides**

*Presented by Leo Schowalter - Lit Thinking*

10:30 Morning Break

### GaN: Going beyond fast charging

11:10 **Achieving Avalanche in GaN-on-silicon Diodes**

*Presented by Farid Medjdoub - University of Lille*

11:25 **Characterizing GaN: Challenges and Advances in Next-Generation Semiconductor Metrology**

*Presented by Áron Pekker - Semilab*

11:40 **X-ray Metrology Solutions for Compound Semiconductors from Labs to Fabs.**

*Presented by Assunta Vigliante - Rigaku*

11:55 **AIXTRON Leading Epitaxy Solutions for High Volume Manufacturing of GaN-based Power Devices**

*Presented by Dr. Nicolas Muesgens - Aixtron*

12:10 **Enhancing Analytical Accuracy of Active Epilayers in Compound Semiconductors by Multi-ion Species Plasma-FIB and Novel**

**STEM Techniques**

*Presented by Antonio Mani - Thermo Fisher Scientific*

12:25 **GaN's Takeover: The Next Big Leap in Power Electronics**

*Presented by Ezgi Dogmus - Yole Group*

12:40 Lunch Break

14:10 **Harnessing the Underestimated Potential of GaN in the Digitalization Revolution: A Catalyst for Unforeseen Innovation in Energy Efficiency**

*Presented by Roberto Crisafulli - STMicroelectronics*

14:25 **Epitaxial GaN Growth using MBE for the Development of Next-Generation Devices**

*Presented by Romain Bruder - Riber*

14:40 **VECTOR: Advancing SEM Metrology with Automation and Versatility**

*Presented by Amanda Wscieklica - Raith*

14:55 **Driving Adoption of GaN for Power Electronics via 300mm Technology**

*Presented by Rudy Parekh - Veeco*

15:10 **Advancement in X-Ray Metrology for High Volume Manufacturing of GaN Based Power Devices**

*Presented by Qian Zheng - Bruker*

15:25 Afternoon Break

### Maintaining momentum for the microLED

16:05 **Perfecting the Polychromatic Pixel**

*Presented by Michelle Chen - Q-Pixel Inc*

16:20 **MicroSolid Printing: Redefining the Future of MicroLED Displays**

*Presented by Reza Chaji - Vue Real*

16:35 **Leveraging NIL for μLED Lens Packaging**

*Presented by Thomas Achleitner - EV Group*

16:50 **The Future of MicroLED Displays: Which Applications Are Leading in 2025?**

*Presented by Raphaël Mermet-Lyaudoz - Yole Group*

17:05 **Pioneering Mass Production and Commercialisation of MicroLED Microdisplays for AR**

*Presented by Kunal Kashyap - Porotech*

17:20 **Revolutionising microLED Displays with Nanowires**

*Presented by Pierre Tchoufian - Aledia*

17:35 Closing Remarks

18:30 Networking Drinks / Dinner Reception

# Day 3 - Wednesday 9th April 2025

08:00 Registration and welcome refreshments

08:50 Housekeeping by Chris Meadows and Tim Bettles - Conference Chairs

## Optimising opportunities for SiC success

09:00 **20 Years of SiC Innovation Leadership: Trench-Assisted Planar Gate Technology**

*Presented by Llewellyn Vaughan-Edmunds - Navitas*

09:15 **Solving Challenges in Compound Semiconductors: An Equipment Supplier's Perspective**

*Presented by David Britz - Applied Materials*

09:30 **Building the World's Biggest SiC Fab**

*Presented by Peter Friedrichs - Infineon*

09:45 **Integrated Metal Etch and Photoresist Strip Solution for SiC Manufacturing**

*Presented by Bernhard Hammerl - Sicconnex Customized Solutions GmbH*

10:00 **High Sensitivity & Throughput Defect Inspection Technologies for SiC and GaN Power Technologies**

*Presented by Mike Rosa - Onto Innovation*

10:15 **SCREEN's Sustainable Cost-of-Ownership (CoO) Portfolio for Wafer Inspection and Thickness Measurement Tools and HVM experience**

*Presented by Alessandro Rossi - SCREEN SPE*

10:30 Morning Break

11:10 **Presentation by Nanotronics**

*Presented by Marius Fischer - Nanotronics*

11:25 **PVA TePla Metrology Solutions for Compound Semiconductors**

*Presented by Frédéric Falise - PVA TePla AG, and Michael Schöler - PVA TePla AG*

11:40 **How Artificial Intelligence Heralds the New Era of Wafering**

*Presented by Malte Mueller - Lapmaster Wolters*

11:55 **Crystal Orientation for Optimizing Quality and Yield throughout the Process Chain**

*Presented by Dirk Kok - Malvern Panalytical*

12:10 **How to save process cost in your SiC/GaN production using best in class power supplies?**

*Presented by Yannick Schneider - TRUMPF*

12:25 Lunch Break

## Ultra-wide bandgap materials: The ultimate devices

Sponsored by Precision Fabricators

13:55 **Prospects of (ultra) Wide Bandgap Oxide ICs**

*Presented by Xiaohang Li - KAUST*

14:10 **A Solution to Doping AlN Enabling a New Era of Nitride Semiconductors**

*Presented by Alan Doolittle - Georgia Institute of Technology*

14:25 **Electric Field Engineering to Unlock the Potential of Gallium Oxide Power Devices**

*Presented by Nolan Hendricks - AFRL (Air Force Research Laboratory)*

14:40 **Efficient Diameter Enlargement of Bulk AlN**

*Presented by Carsten Hartmann - Leibniz-Institut für Kristallzüchtung (IKZ)*

14:55 **The promise of cubic Boron Nitride (c-BN)**

*Presented by Siddha Pimputkar - Lehigh University*

15:10 Closing Remarks

